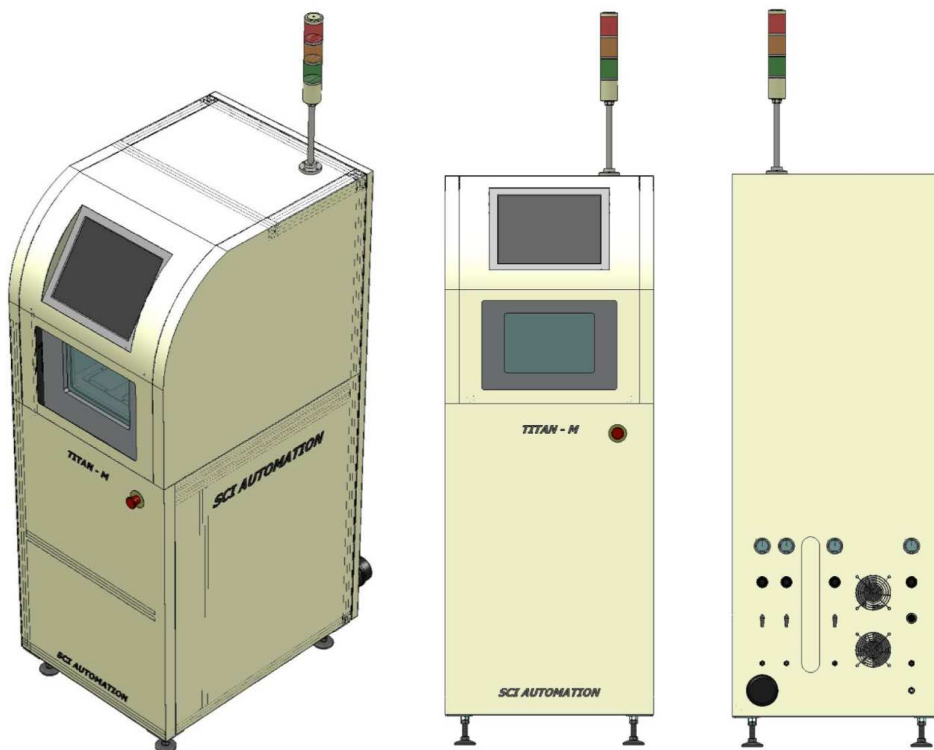


Plasma Technology



**TITAN IS A COMPACT
PLASMA CLEANING SYSTEM SUITABLE
FOR STANDALONE OPERATION.**

TITAN

Version M

Process gases:

- AR/H₂ 95/5%
- N₂/H₂ 95/5%
- AR/O₂ In Various Mix ranges
- O₂
- Other gases on request

Pressure Operating Range:

- Standard: 0.1 to 1 mbar
- Turbo: 0.005 to 0.1 mbar

Options:

- Electrode Configuration
- Chamber Size
- Turbo Pump
- Hydrogen Generator
- 600 Watt RF Generator
- Extra Gas line

Applications:

- Cleaning of copper leadframes prior to wire bonding
- Organic decontamination prior to wire bonding
- Adhesion promoter prior to molding
- Adhesion promoter of die attach materials on leadframes or PBGA strips
- Flux removal from semiconductor packages or hybrids
- General activation, cleaning and decontamination
- Adhesion promoter for flip chip packages prior to Underfill
- Wafer Cleaning and Activation
- Hard Disk applications
- Solar applications

Specifications:

- Machine dimensions: 694 x 950 x 1850 (h) mm
- Weight: 500 kg.
- Power: Single Phase 100-240 V 50 /60Hz, 2.5 KVA
- Air: Dry 3—6 bar
- Chamber material: aluminum
- Standard chamber capacity: 3 slotted magazines 300 x 200 x 100 mm or more of smaller dimensions.
- Custom chamber sizes: Optional
- Electrode assembly: 2 planar or 1 barrel
- Pressure sensor: Baratron range, 1 to 0.0001 mbar
- 2 gas lines with mass flow controller
- Input pressure sensor on each gas line
- N₂ purge line
- Dry pump (low maintenance)
- 300 watt RF generator @ 13.56 MHz
- Automatic matching network
- Controller: PC with distributed I/Os
- HMI: 17" LCD touch screen
- Clean Room Compatible
- CE & ISO 9001 certified

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